



**SDI Review Form 1.6**

Journal Name:	<a href="#">Journal of Engineering Research and Reports</a>
Manuscript Number:	Ms_JERR_51011
Title of the Manuscript:	Estimation of Solder Ball Collapse Height in Semiconductor Packaging using Theoretical and Solid Modeling Techniques
Type of the Article	

**General guideline for Peer Review process:**

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

**PART 1: Review Comments**

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
<b>Compulsory</b> REVISION comments		
<b>Minor</b> REVISION comments	1. Dependencies presented are not numbered.  2. It is not accepted in formulas to spell words. Formulas should contain the letters of the corresponding quantities, which should be described and explained - page 4.	Equations now numbered in the revised manuscript. Equation using word now replaced with letter ( $\Delta V$ ). → Highlighted in yellow (refer to the revised manuscript)  Thanks for the review inputs.
<b>Optional/General</b> comments		

**PART 2:**

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	(If yes, Kindly please write down the ethical issues here in details)	